

Title (en)
RESIST COMPOSITION

Title (de)
RESISTZUSAMMENSETZUNG

Title (fr)
COMPOSITION DE MATIERE DE RESERVE

Publication
EP 1644777 A2 20060412 (EN)

Application
EP 04747446 A 20040706

Priority

- JP 2004009980 W 20040706
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Abstract (en)
[origin: WO2005003859A2] There is provided a resist composition used for the production of printed boards, which comprises (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains: (D-1) at least one organic solvent selected from the group consisting of an (-hydroxycarboxylate ester, a (-alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative, and (D-2) an organic solvent having a hydroxyl group other than (D-1).

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G03F 7/004

IPC 8 full level
G03F 7/00 (2006.01); **G03F 7/004** (2006.01); **G03F 7/027** (2006.01); **G03F 7/033** (2006.01)

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See references of WO 2005003859A2

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